

Automotive MOSFET

OptiMOS™ 7 Power-Transistor







Features

- OptiMOS[™] power MOSFET for automotive applications
- N-channel Enhancement mode Logic Level
- Extended qualification beyond AEC-Q101
- Enhanced electrical testing
- Robust design
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- RoHS compliant
- 100% Avalanche tested

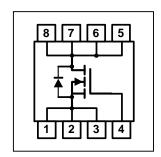
Potential applications

General automotive applications.

Product validation

Qualified for automotive applications. Product validation according to AEC-Q101.





Product Summary

V_{DS}	40	V
R _{DS(on)}	0.91	mΩ
I _D (chip limited)	275	Α

Туре	Package	Marking
IAUCN04S7L009	PG-TDSON-8-34	7N04L009

IAUCN04S7L009



Table of Contents

Description	1
Maximum ratings	3
Thermal characteristics	4
Electrical characteristics	4
Electrical characteristics diagrams	6
Package outline & footprint	10
Revision history	11
Disclaimer	12

IAUCN04S7L009



Maximum ratings

at Tj=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I _D	V _{GS} =10 V, Chip limitation ^{1,2)}	275	А
		V _{GS} =10V, DC current	175	
		T_a =100 °C, V_{GS} =10 V, R_{thJA} on 2s2p ^{2,3)}	40	
Pulsed drain current ²⁾	I _{D,pulse}	T _C =25 °C, t _p = 100 μs	840]
Avalanche energy, single pulse ²⁾	E AS	/ _D =67 A	145	mJ
Avalanche current, single pulse	I _{AS}	-	133	А
Gate source voltage	V _{GS}	-	±16	V
		limited to duty factor of 1%	+20	V
Power dissipation	P tot	Т _С =25 °С	129	W
Operating and storage temperature	$T_{\rm j}$, $T_{\rm stg}$	-	-55 + 175	°C

IAUCN04S7L009



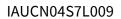
Thermal characteristics²⁾

Parameter	Symbol	Conditions	Values		Unit	
			min.	typ.	max.]
Thermal resistance, junction - case	R thJC	-	-	0.6	1.2	K/W
Thermal resistance, junction - ambient ³⁾	R _{thJA}	-	-	27	-	

Electrical characteristics

at Tj=25 °C, unless otherwise specified

Parameter	Symbol	Symbol Conditions	Values			Unit
			min.	typ.	max.	
Static characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V_{GS} =0 V, I_{D} =1 mA	40	_	-	V
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 60 \mu A$	1.2	1.5	1.8	
Zero gate voltage drain current	I _{DSS}	$V_{\rm DS}$ =40 V, $V_{\rm GS}$ =0 V, $T_{\rm j}$ =25 °C	-	_	1	μΑ
		V_{DS} =40 V, V_{GS} =0 V, T_{j} =100 °C ²)	-	-	14	
Gate-source leakage current	I _{GSS}	V _{GS} =16 V, V _{DS} =0 V	-	-	100	nA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =4.5 V, I _D =88 A	-	1.10	1.29	mΩ
		V _{GS} =10 V, I _D =88 A	_	0.80	0.91	
Gate resistance ²⁾	R _G	-	-	1.2	_	Ω





Parameter	Symbol Conditions		Values			Unit
			min.	typ.	max.	
Dynamic characteristics ²⁾						
Input capacitance	C iss		-	4388	5704	pF
Output capacitance	C oss	V_{GS} =0 V, V_{DS} =20 V, f =1 MHz	-	2203	2860	
Reverse transfer capacitance	C _{rss}		-	75	112	
Turn-on delay time	t _{d(on)}		-	5	-	ns
Rise time	t r	V_{DD} =20 V, V_{GS} =10 V, I_{D} =88 A,	-	5	-	
Turn-off delay time	t d(off)	$R_{\rm G}$ =3.5 Ω	-	40	-	
Fall time	t f]	_	19	-	
Gate to drain charge Gate charge total	Q gs Q gd	V _{DD} =20 V, I _D =88 A, V _{GS} =0 to 10 V	-	12 11	15 17	nC
Gate charge total	Q _g		-	66	85	
Gate plateau voltage	$V_{ m plateau}$		-	2.7	-	V
Reverse Diode						
Diode continous forward current ²⁾	I _S	Т _C =25 °С	-	-	175	А
Diode pulse current ²⁾	/ _{S,pulse}	T _C =25 °C, t _p = 100 μs	-	-	840	
Diode forward voltage	V_{SD}	$V_{\rm GS}$ =0 V, $I_{\rm F}$ =88 A, $T_{\rm j}$ =25 °C	-	0.8	0.95	V
Reverse recovery time ²⁾	t rr	V_R =20 V, I_F =50A, d i_F /d t =100 A/ μ s	-	41	61	ns
Reverse recovery charge ²⁾	Q rr		_	32	64	nC

¹⁾ Practically the current is limited by the overall system design including the customer-specific PCB.

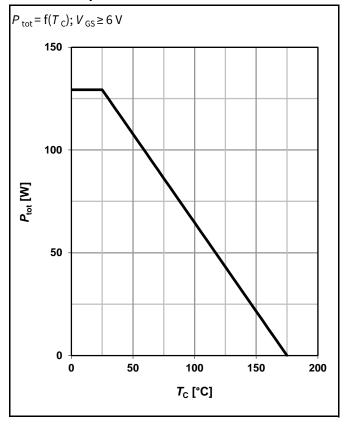
²⁾ The parameter is not subject to production testing – specified by design.

³⁾ Device on 2s2p FR4 PCB defined in accordance with JEDEC standards (JESD51-5, -7). PCB is vertical in still air.

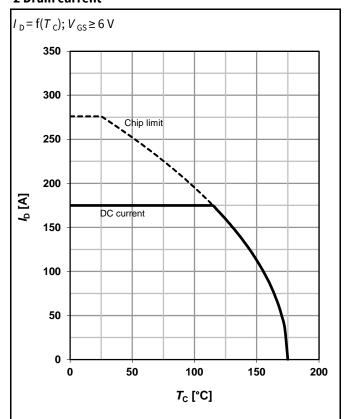


Electrical characteristics diagrams

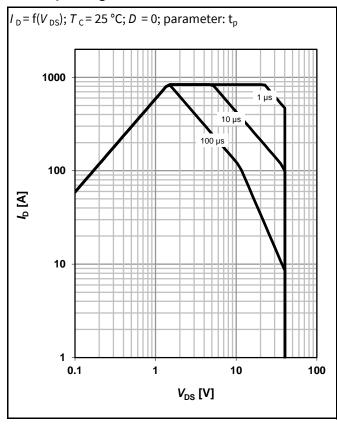
1 Power dissipation



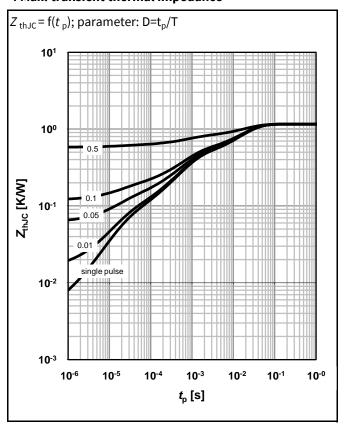
2 Drain current



3 Safe operating area

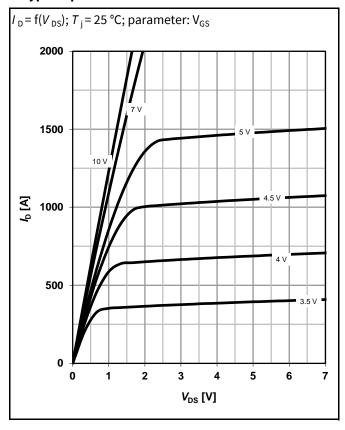


4 Max. transient thermal impedance

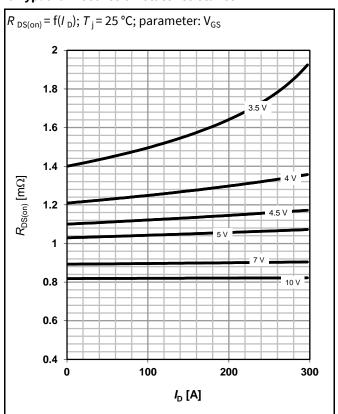




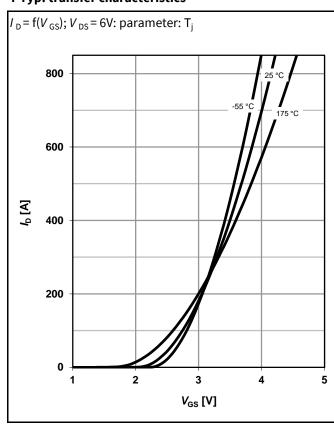
5 Typ. output characteristics



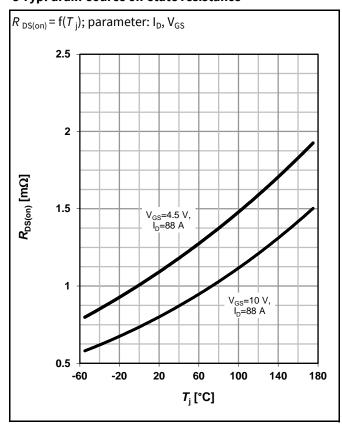
6 Typ. drain-source on-state resistance



7 Typ. transfer characteristics

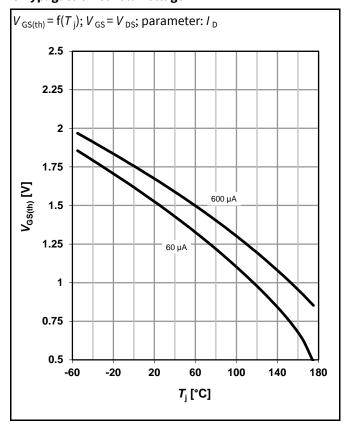


8 Typ. drain-source on-state resistance

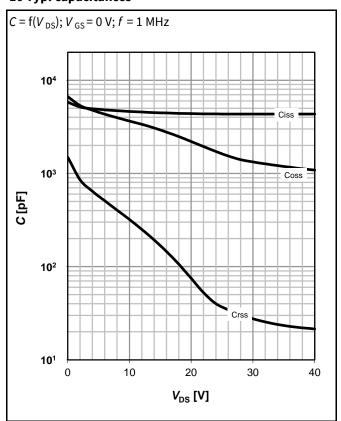


infineon

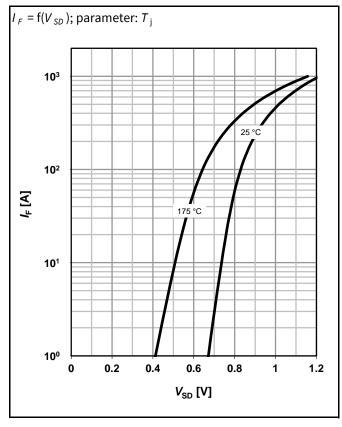
9 Typ. gate threshold voltage



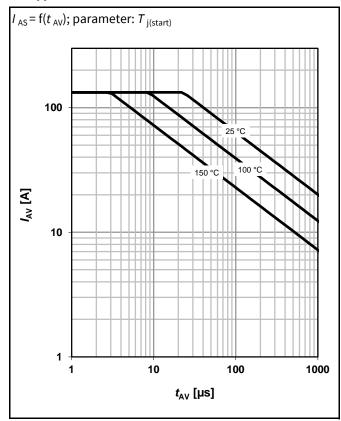
10 Typ. capacitances



11 Typical forward diode characteristics

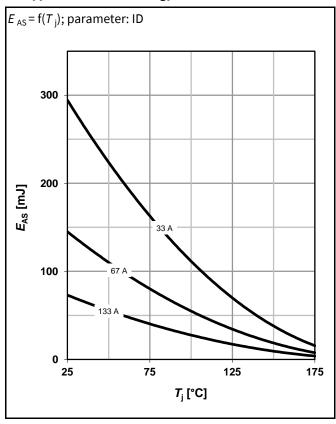


12 Typ. avalanche characteristics

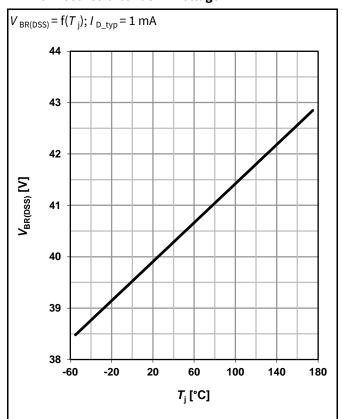


infineon

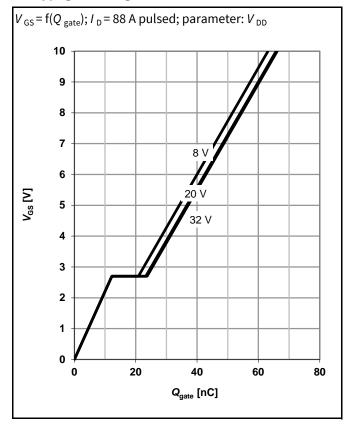
13 Typical avalanche energy



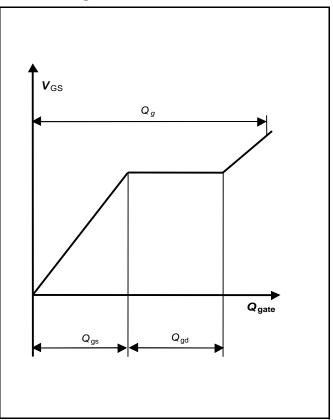
14 Drain-source breakdown voltage



15 Typ. gate charge

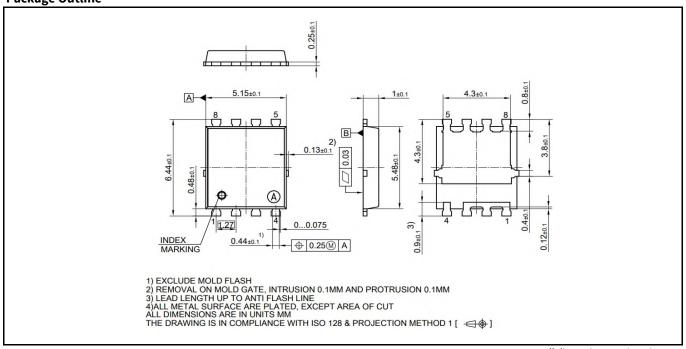


16 Gate charge waveforms



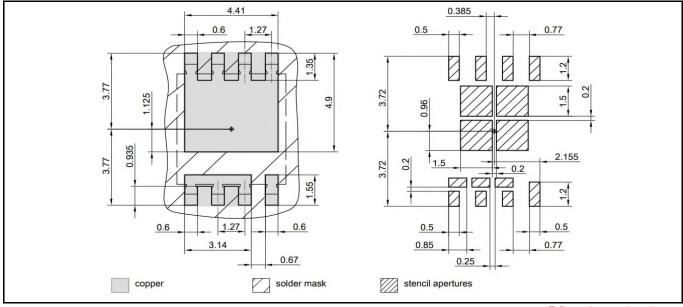


Package Outline



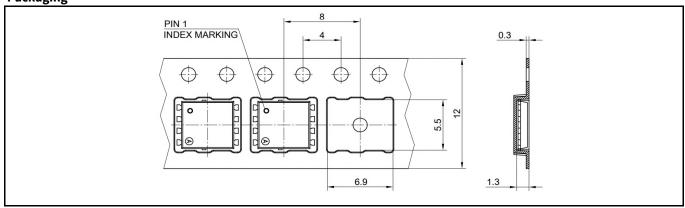
All dimensions are in units mm

Footprint



All dimensions are in units mm

Packaging



All dimensions are in units mm

IAUCN04S7L009



Revision History

Revision	Date	Changes
Revision 1.0	15.11.2023	Final Data Sheet

Trademarks

All referenced product or service names and trademarks are the property of their respective owners.

Edition 2023-11-15

Published by

Infineon Technologies AG

81726 Munich, Germany

© 2023 Infineon Technologies AG

All Rights Reserved.

Do you have any questions about any aspect of this document?

Email: erratum@infineon.com

Document reference IAUCN04S7L009-Data-Sheet-10-Infineon

IMPORTANT NOTICE

regarded as a guarantee of conditions or characteristics ("Beschaffenheitsgarantie").

With respect to any examples, hints or any typical values stated herein and/or any information regarding the application of the product, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

In addition, any information given in this document is subject to customer's compliance with its obligations stated in this document and any applicable legal requirements, norms and standards concerning customer's products and any use of the product of Infineon Technologies in customer's applications. The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of customer's technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to such application.

The information given in this document shall in no event be For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office (<u>www.infineon.com</u>).

WARNINGS

Due to technical requirements products may contain dangerous substances. For information on the types in question please contact the nearest Infineon Technologies

Except as otherwise explicitly approved by Infineon Technologies in a written document signed by authorized representatives of Infineon Technologies, Infineon Technologies' products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal